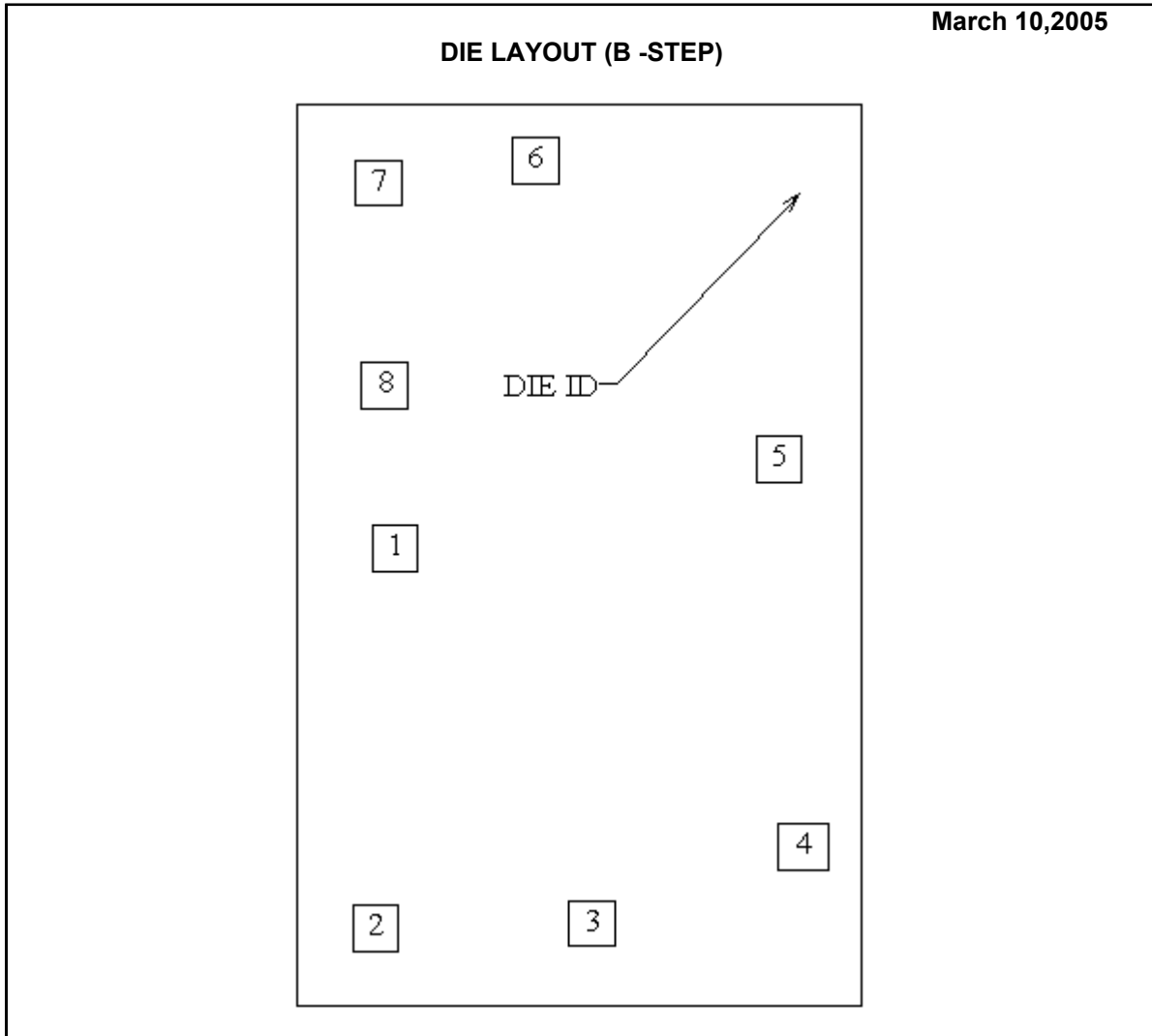


**LM6164 MD8
HIGH SPEED OPERATIONAL AMPLIFIER**



DIE/WAFER CHARACTERISTICS

Fabrication Attributes		General Die Information	
Physical Die Identification	LM6164B	Bond Pad Opening Size (min)	102 μ m x 102 μ m
Die Step	B	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	100mm	Back Side Metal	Bare Back
Die Size (Drawn)	1270 μ m x 2032 μ m 50.0mils x 80.0mils	Back Side Connection	Floating
Thickness	330 μ m Nominal		
Min Pitch	354 μ m Nominal		

Special Assembly Requirements:

Note: Actual die size is rounded to the nearest micron.

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Die Bond Pad Coordinate Locations (B -Step)						
(Referenced to die center, coordinates in μm) NC = No Connection, N.U. = Not Used						
SIGNAL	PAD#	X/Y COORDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
VOS ADJ	1	-416	15	102	x	102
INPUT -	2	-460	-842	102	x	102
INPUT +	3	29	-831	102	x	102
V+	4	505	-658	112	x	102
NC	5	452	217	102	x	102
VOUT	6	-99	890	102	x	102
V+	7	-453	841	102	x	102
VOS ADJ	8	-440	383	102	x	102

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